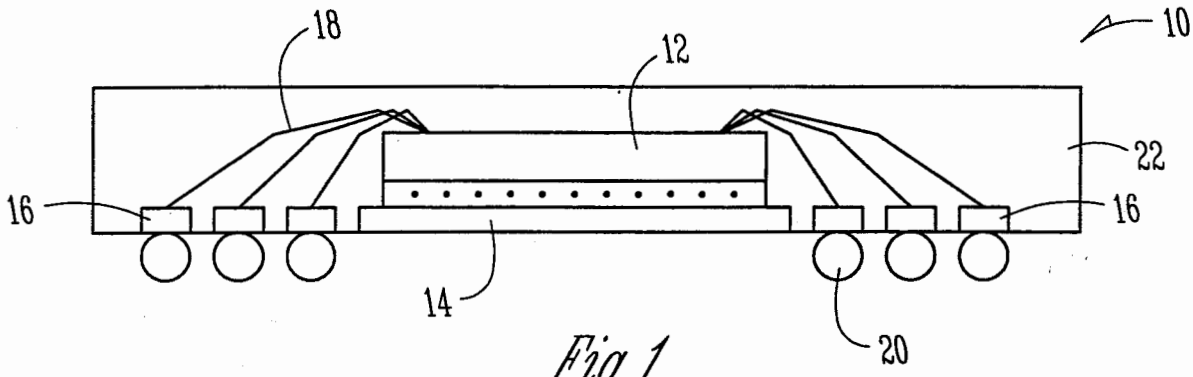


Fig. 1

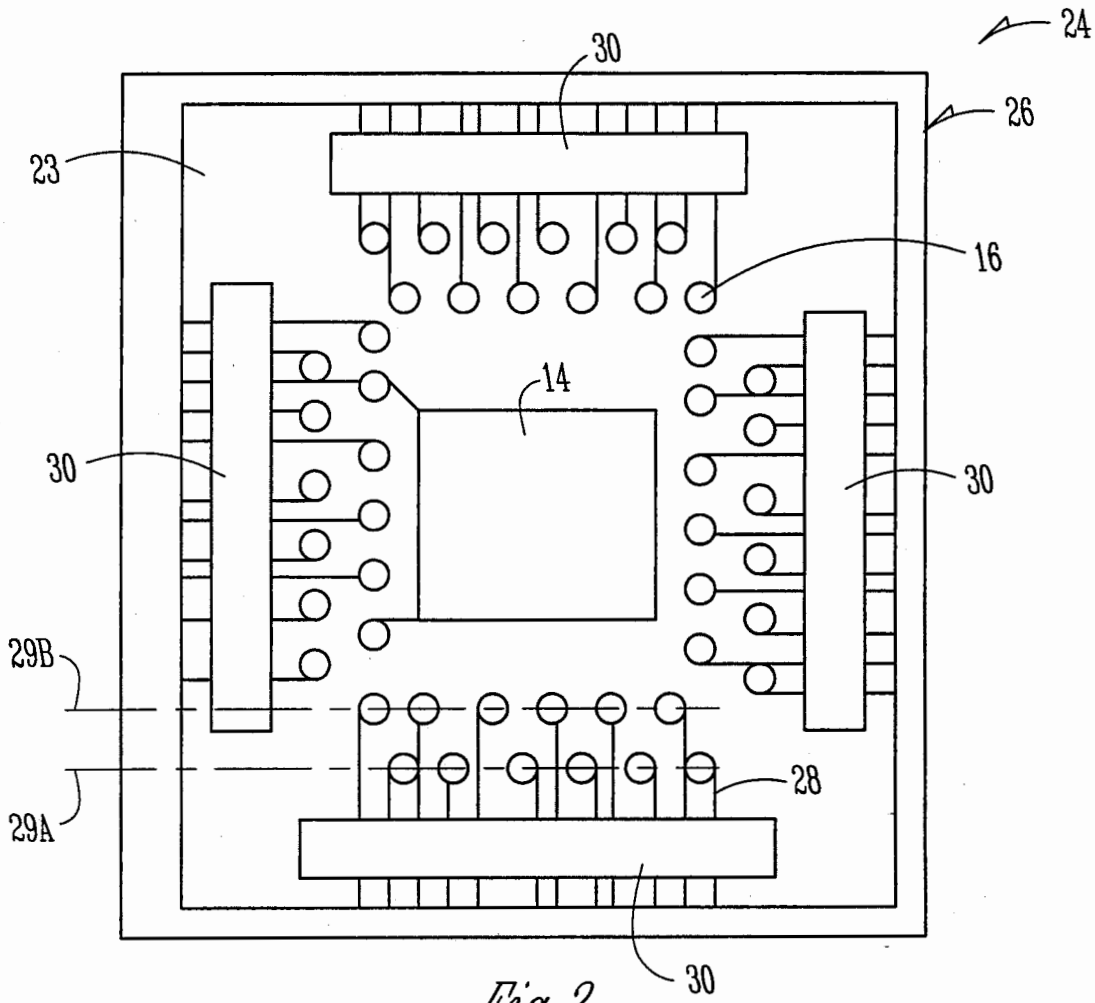


Fig. 2

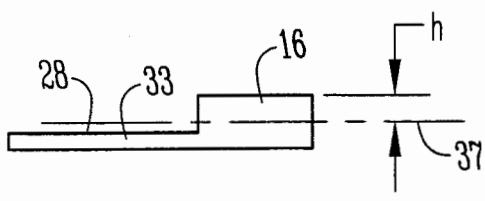


Fig. 3

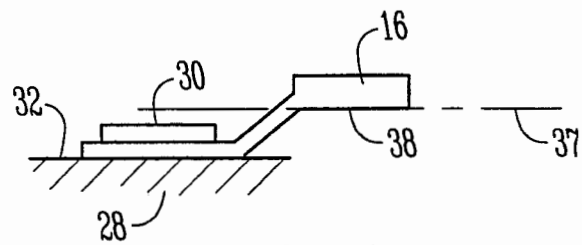


Fig. 4

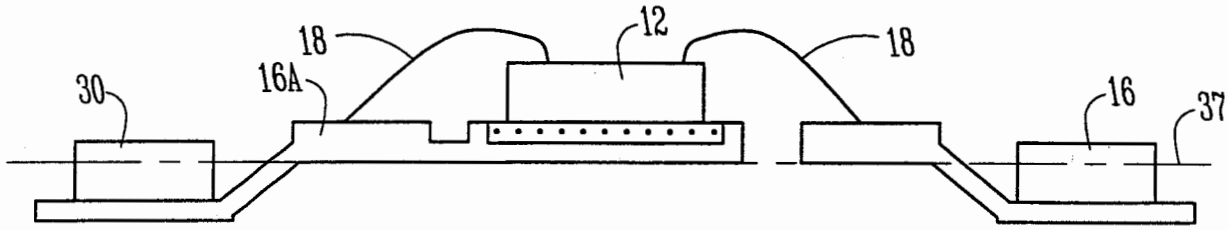


Fig. 5

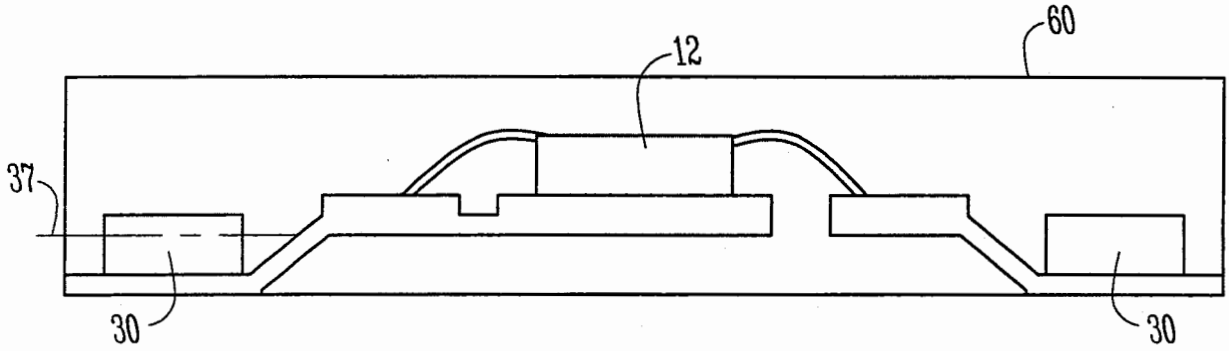


Fig. 6

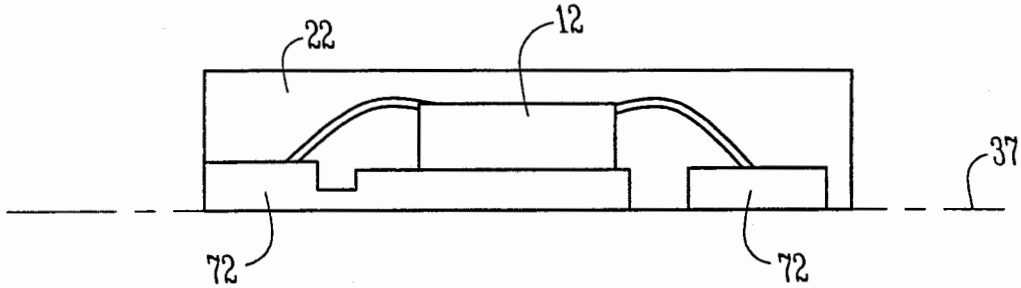


Fig. 7

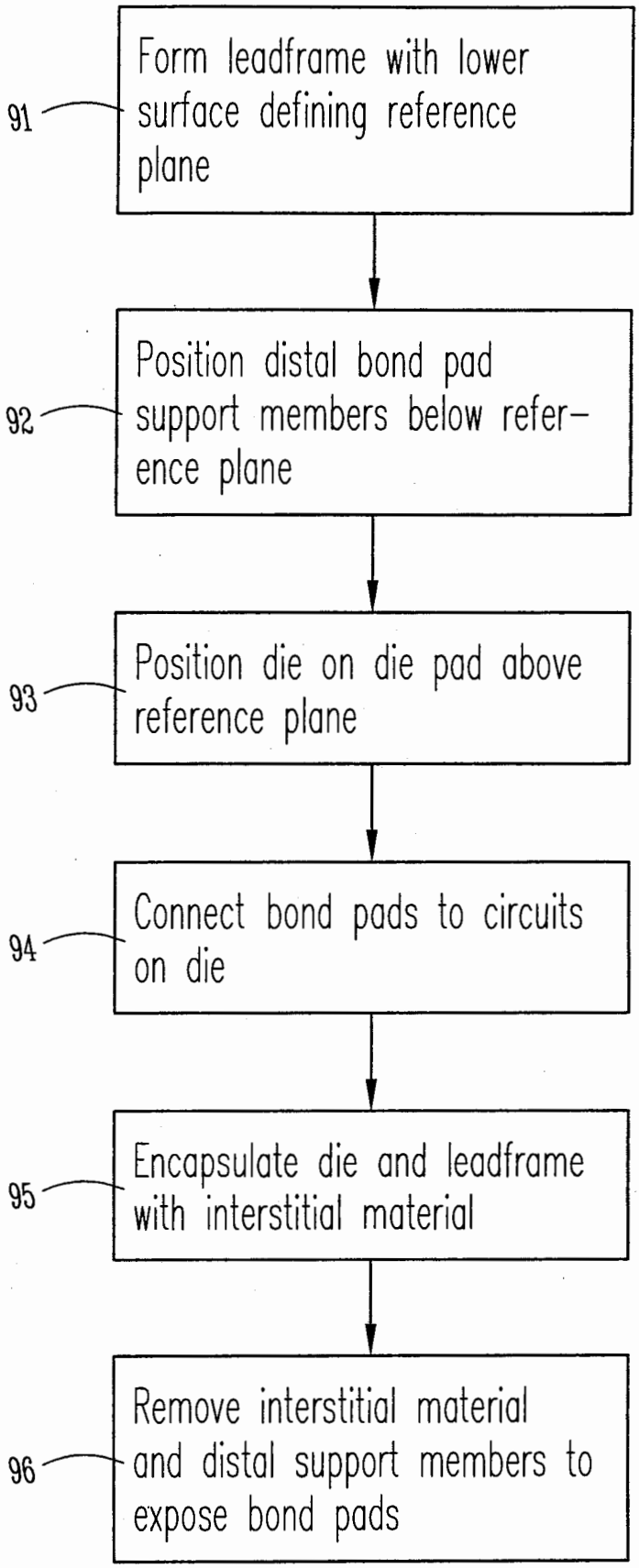

91
Form leadframe with lower surface defining reference plane
92
Position distal bond pad support members below reference plane
93
Position die on die pad above reference plane
94
Connect bond pads to circuits on die
95
Encapsulate die and leadframe with interstitial material
96
Remove interstitial material and distal support members to expose bond pads

Fig. 8